

LNJ811R8DRU

Surface Mounting Chip LED

3216 FD Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	60	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	100	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color

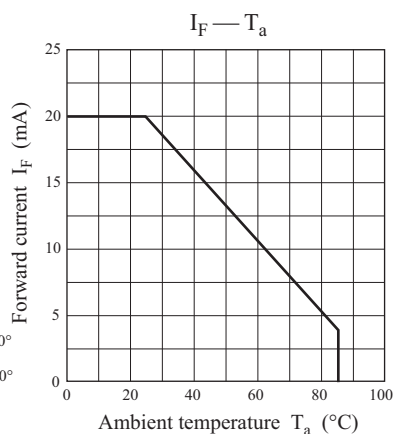
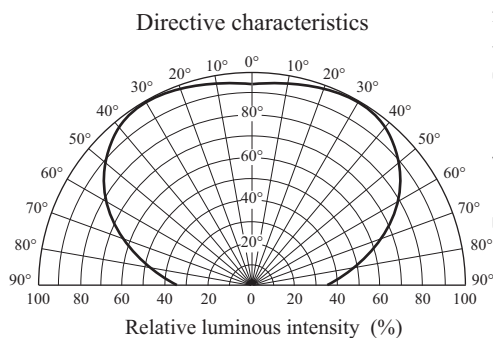
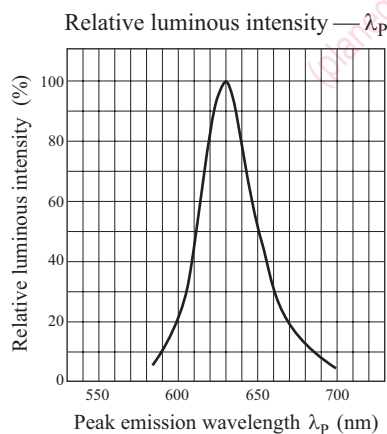
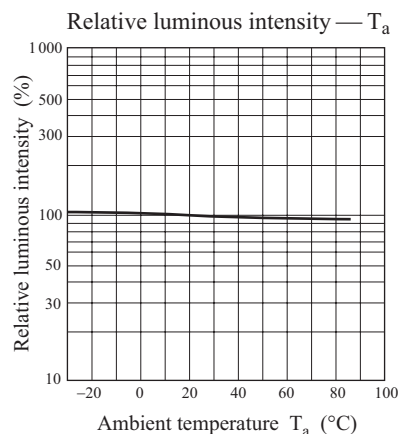
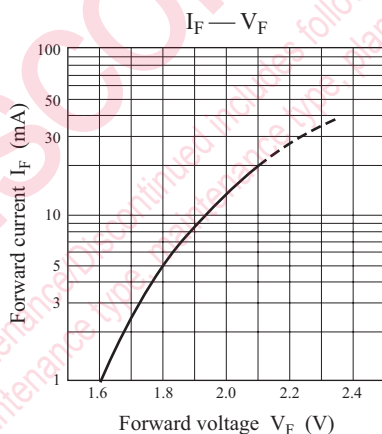
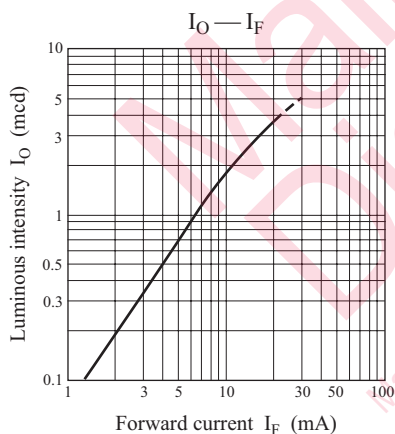
- Orange

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

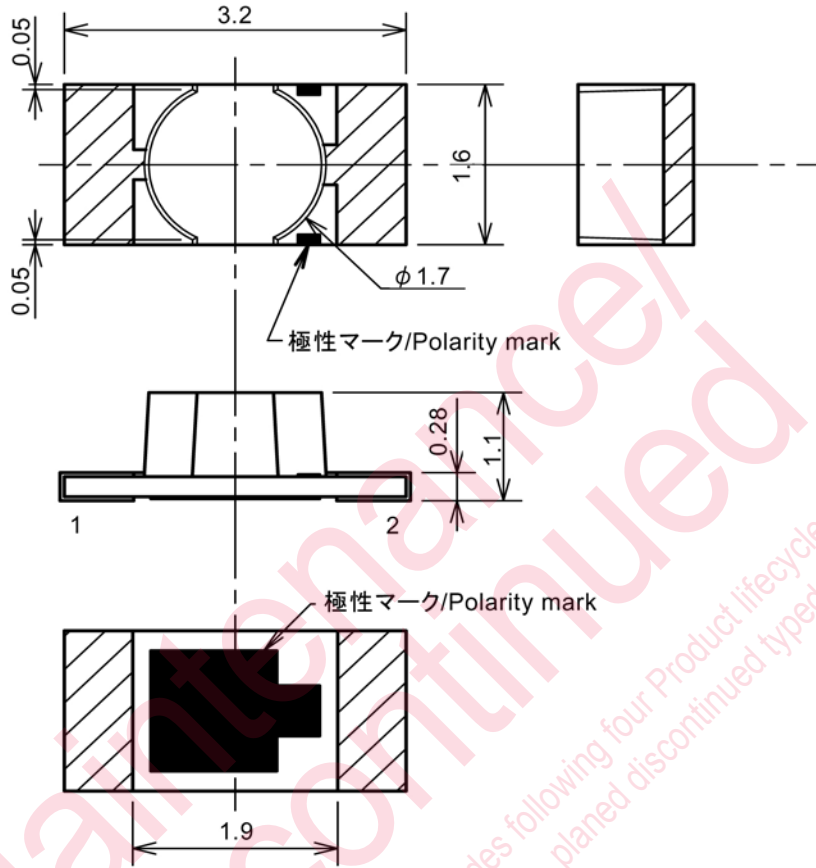
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 10 \text{ mA}$	0.7	1.8		mcd
Reverse current	I_R	$V_R = 3 \text{ V}$			10	μA
Forward voltage	V_F	$I_F = 10 \text{ mA}$		1.93	2.6	V
Peak emission wavelength	λ_p	$I_F = 10 \text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		40		nm

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

KLTFN2K1100



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued includes following four Product lifecycle stage.
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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